Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

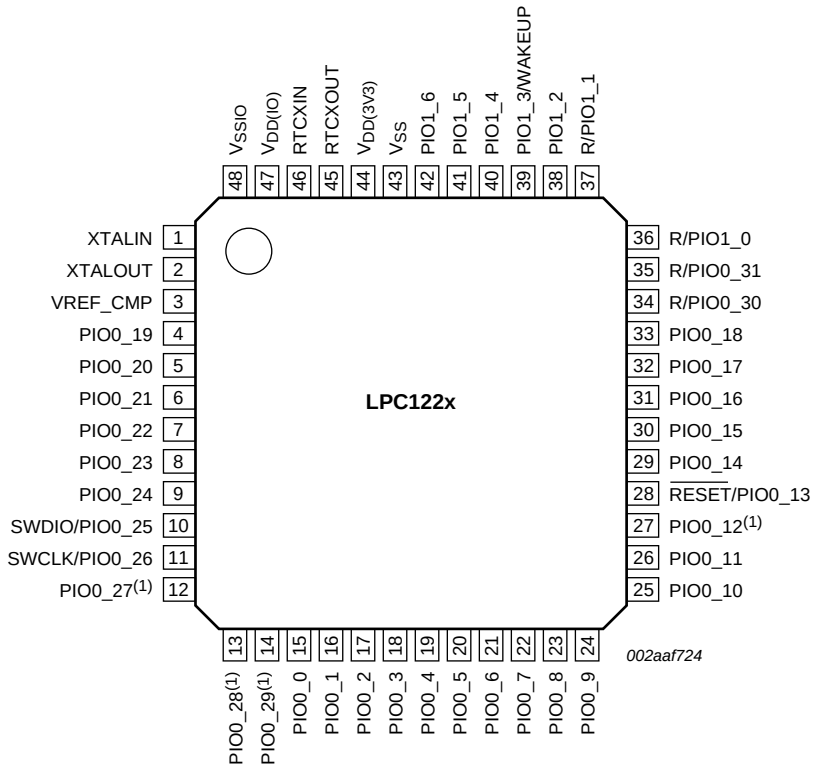
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	45MHz
Connectivity	I²C, IrDA, Microwire, SPI, SSI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, WDT
Number of I/O	55
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc1226fbd64-301-1

4.1 Ordering options

Table 2. Ordering options for LPC122x

Type number	Flash	Total SRAM	UART	I^2C/ FM+	SSP/ SPI	ADC channels	GPIO	Package
LPC1227								
LPC1227FBD64/301	128 kB	8 kB	2	1	1	8	55	LQFP64
LPC1227FBD48/301	128 kB	8 kB	2	1	1	8	39	LQFP48
LPC1226								
LPC1226FBD64/301	96 kB	8 kB	2	1	1	8	55	LQFP64
LPC1226FBD48/301	96 kB	8 kB	2	1	1	8	39	LQFP48
LPC1225								
LPC1225FBD64/321	80 kB	8 kB	2	1	1	8	55	LQFP64
LPC1225FBD64/301	64 kB	8 kB	2	1	1	8	55	LQFP64
LPC1225FBD48/321	80 kB	8 kB	2	1	1	8	39	LQFP48
LPC1225FBD48/301	64 kB	8 kB	2	1	1	8	39	LQFP48
LPC1224								
LPC1224FBD64/121	48 kB	4 kB	2	1	1	8	55	LQFP64
LPC1224FBD64/101	32 kB	4 kB	2	1	1	8	55	LQFP64
LPC1224FBD48/121	48 kB	4 kB	2	1	1	8	39	LQFP48
LPC1224FBD48/101	32 kB	4 kB	2	1	1	8	39	LQFP48



(1) High-current output driver.

Remark: For a full listing of all functions for each pin see Table 3.

Fig 3. Pin configuration LQFP48 package

Table 3. LPC122x pin description *…continued*

Symbol	Pin LQFP48	Pin LQFP64		Start logic input	Type	Reset state [1]	Description
PIO0_7/$\overline{\text{CTS0}}$/ CT32B1_CAP1/ CT32B1_MAT1	22	26	[2] [3]	yes	I/O	I; PU	**PIO0_7 —** General purpose digital input/output pin.
					I	-	**$\overline{\text{CTS0}}$ —** Clear To Send input for UART0.
					I	-	**CT32B1_CAP1 —** Capture input, channel 1 for 32-bit timer 1.
					O	-	**CT32B1_MAT1 —** Match output, channel 1 for 32-bit timer 1.
PIO0_8/RXD1/ CT32B1_CAP2/ CT32B1_MAT2	23	27	[2] [3]	yes	I/O	I; PU	**PIO0_8 —** General purpose digital input/output pin.
					I	-	**RXD1 —** Receiver input for UART1.
					I	-	**CT32B1_CAP2 —** Capture input, channel 2 for 32-bit timer 1.
					O	-	**CT32B1_MAT2 —** Match output, channel 2 for 32-bit timer 1.
PIO0_9/TXD1/ CT32B1_CAP3/ CT32B1_MAT3	24	28	[2] [3]	yes	I/O	I; PU	**PIO0_9 —** General purpose digital input/output pin.
					O	-	**TXD1 —** Transmitter output for UART1.
					I	-	**CT32B1_CAP3 —** Capture input, channel 3 for 32-bit timer 1.
					O	-	**CT32B1_MAT3 —** Match output, channel 3 for 32-bit timer 1.
PIO0_10/SCL	25	37	[4]	yes	I/O	I; IA	**PIO0_10 —** General purpose digital input/output pin.
					I/O	-	**SCL —** I^2C-bus clock input/output.
PIO0_11/SDA/ CT16B0_CAP0/ CT16B0_MAT0	26	38	[4]	yes	I/O	I; IA	**PIO0_11 —** General purpose digital input/output pin.
					I/O	-	**SDA —** I^2C-bus data input/output.
					I	-	**CT16B0_CAP0 —** Capture input, channel 0 for 16-bit timer 0.
					O	-	**CT16B0_MAT0 —** Match output, channel 0 for 16-bit timer 0.
PIO0_12/CLKOUT/ CT16B0_CAP1/ CT16B0_MAT1	27	39	[9]	no	I/O	I; PU	**PIO0_12 —** General purpose digital input/output pin. A LOW level on this pin during reset starts the ISP command handler. High-current output driver.
					O	-	**CLKOUT —** Clock out pin.
					I	-	**CT16B0_CAP1 —** Capture input, channel 1 for 16-bit timer 0.
					O	-	**CT16B0_MAT1 —** Match output, channel 1 for 16-bit timer 0.
$\overline{\text{RESET}}$/PIO0_13	28	40	[5] [3]	no	I	I; PU	**$\overline{\text{RESET}}$ —** External reset input: A LOW on this pin resets the device, causing I/O ports and peripherals to take on their default states, and processor execution to begin at address 0.
					I/O	-	**PIO0_13 —** General purpose digital input/output pin.
PIO0_14/SCK	29	41	[2] [3]	no	I/O	I; PU	**PIO0_14 —** General purpose digital input/output pin.
					I/O	-	**SCK —** Serial clock for SSP/SPI.
PIO0_15/SSEL/ CT16B1_CAP0/ CT16B1_MAT0	30	42	[2] [3]	no	I/O	I; PU	**PIO0_15 —** General purpose digital input/output pin.
					I/O	-	**SSEL —** Slave select for SSP/SPI.
					I	-	**CT16B1_CAP0 —** Capture input, channel 0 for 16-bit timer 1.
					O	-	**CT16B1_MAT0 —** Match output, channel 0 for 16-bit timer 1.
PIO0_16/MISO/ CT16B1_CAP1/ CT16B1_MAT1	31	43	[2] [3]	no	I/O	I; PU	**PIO0_16 —** General purpose digital input/output pin.
					I/O	-	**MISO —** Master In Slave Out for SSP/SPI.
					I	-	**CT16B1_CAP1 —** Capture input, channel 1 for 16-bit timer 1.
					O	-	**CT16B1_MAT1 —** Match output, channel 1 for 16-bit timer 1.

Table 3. LPC122x pin description *…continued*

Symbol	Pin LQFP48	Pin LQFP64	Start logic input	Type	Reset state [1]	Description
$V_{DD(IO)}$	47	63	-	I	-	Input/output supply voltage.
$V_{DD(3V3)}$	44	56	-	I	-	3.3 V supply voltage to the internal regulator and the ADC. Also used as the ADC reference voltage.
V_{SSIO}	48	64	-	I	-	Ground.
V_{SS}	43	55	-	I	-	Ground.

[1] Pin state at reset for default function: I = Input; O = Output; PU = internal pull-up enabled; IA = inactive, no pull-up/down enabled.

[2] 3.3 V tolerant, digital I/O pin; default: pull-up enabled, no hysteresis.

[3] If set to output, this normal-drive pin is in low mode by default.

[4] I^2C-bus pins; 5 V tolerant; open-drain; default: no pull-up/pull-down; no hysteresis.

[5] 3.3 V tolerant, digital I/O pin with $\overline{\text{RESET}}$ function; default: pull-up enabled, no hysteresis. An external pull-up resistor is required on this pin for the Deep power-down mode.

[6] 3.3 V tolerant, digital I/O pin with analog function; default: pull-up enabled, no hysteresis.

[7] If set to output, this normal-drive pin is in high mode by default.

[8] 3.3 V tolerant, digital I/O pin with analog function and WAKEUP function; default: pull-up enabled, no hysteresis.

[9] 3.3 V tolerant, high-drive digital I/O pin; default: pull-up enabled, no hysteresis.

[10] If the RTC is not used, RTCXIN and RTCXOUT can be left floating.

To enable a peripheral function, find the corresponding port pin, or select a port pin if the function is multiplexed, and program the port pin's IOCONFIG register to enable that function. The primary SWD functions and $\overline{\text{RESET}}$ are the default functions on their pins after reset.

Table 4. Pin multiplexing

Peripheral	Function	Type	Available on ports:		
Analog comparators	ROSC	I/O	PIO0_29	-	-
	ACMP0_I0	I	PIO0_19	-	-
	ACMP0_I1	I	PIO0_20	-	-
	ACMP0_I2	I	PIO0_21	-	-
	ACMP0_I3	I	PIO0_22	-	-
	ACMP0_O	O	PIO0_27	-	-
	ACMP1_I0	I	PIO0_23	-	-
	ACMP1_I1	I	PIO0_24	-	-
	ACMP1_I2	I	PIO0_25	-	-
	ACMP1_I3	I	PIO0_26	-	-
	ACMP1_O	O	PIO0_28	-	-

Table 4. Pin multiplexing

Peripheral	Function	Type	Available on ports:		
ADC	AD0	I	PIO0_30	-	-
	AD1	I	PIO0_31	-	-
	AD2	I	PIO1_0	-	-
	AD3	I	PIO1_1	-	-
	AD4	I	PIO1_2	-	-
	AD5	I	PIO1_3	-	-
	AD6	I	PIO1_4	-	-
	AD7	I	PIO1_5	-	-
CT16B0	CT16B0_CAP0	I	PIO0_11	PIO0_28	PIO2_0
	CT16B0_CAP1	I	PIO0_12	PIO0_29	PIO2_1
	CT16B0_MAT0	O	PIO0_11	PIO0_28	PIO2_0
	CT16B0_MAT1	O	PIO0_12	PIO0_29	PIO2_1
CT16B1	CT16B1_CAP0	I	PIO0_15	PIO1_5	PIO2_2
	CT16B1_CAP1	I	PIO0_16	PIO1_6	PIO2_3
	CT16B1_MAT0	O	PIO0_15	PIO1_5	PIO2_2
	CT16B1_MAT1	O	PIO0_16	PIO1_6	PIO2_3
CT32B0	CT32B0_CAP0	I	PIO0_1	PIO0_18	PIO2_4
	CT32B0_CAP1	I	PIO0_2	PIO0_19	PIO2_5
	CT32B0_CAP2	I	PIO0_3	PIO0_20	PIO2_6
	CT32B0_CAP3	I	PIO0_4	PIO0_21	PIO2_7
	CT32B0_MAT0	O	PIO0_1	PIO0_18	PIO2_4
	CT32B0_MAT1	O	PIO0_2	PIO0_19	PIO2_5
	CT32B0_MAT2	O	PIO0_3	PIO0_20	PIO2_6
	CT32B0_MAT3	O	PIO0_4	PIO0_21	PIO2_7
CT32B1	CT32B1_CAP0	I	PIO0_6	PIO0_23	PIO2_8
	CT32B1_CAP1	I	PIO0_7	PIO0_24	PIO2_9
	CT32B1_CAP2	I	PIO0_8	PIO0_25	PIO2_10
	CT32B1_CAP3	I	PIO0_9	PIO0_26	PIO2_11
	CT32B1_MAT0	O	PIO0_6	PIO0_23	PIO2_8
	CT32B1_MAT1	O	PIO0_7	PIO0_24	PIO2_9
	CT32B1_MAT2	O	PIO0_8	PIO0_25	PIO2_10
	CT32B1_MAT3	O	PIO0_9	PIO0_26	PIO2_11
UART0	RXD0	I	PIO0_1	PIO2_1	-
	TXD0	O	PIO0_2	PIO2_2	-
	$\overline{\text{CTS0}}$	I	PIO0_7	PIO2_4	-
	$\overline{\text{DCD0}}$	I	PIO0_5	PIO2_6	-
	$\overline{\text{DSR0}}$	I	PIO0_4	PIO2_7	-
	$\overline{\text{DTR0}}$	O	PIO0_3	PIO2_3	-
	$\overline{\text{RI0}}$	I	PIO0_6	PIO2_5	-
	$\overline{\text{RTS0}}$	O	PIO0_0	PIO2_0	-

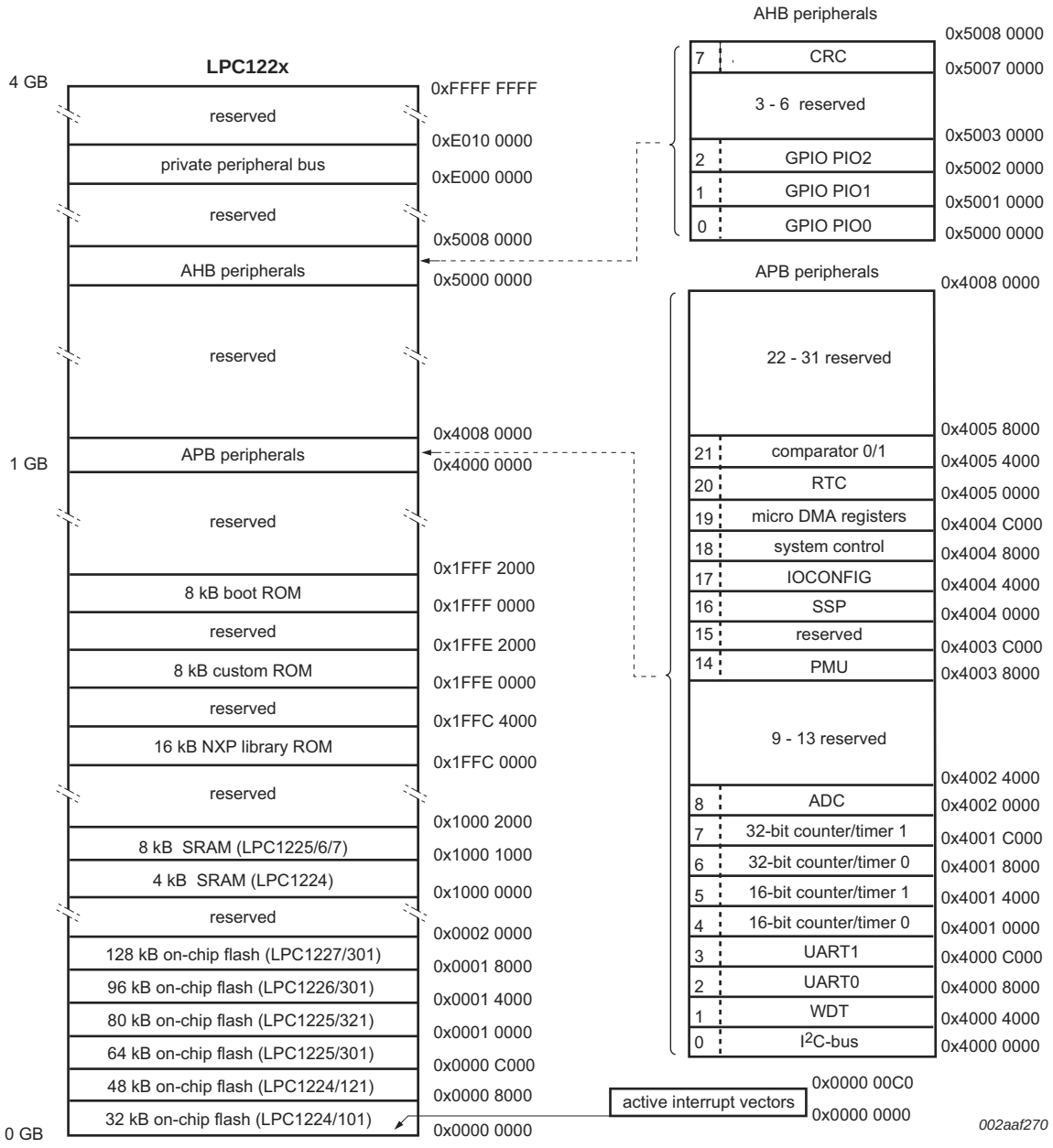


Fig 4. LPC122x memory map

7.5 Nested Vectored Interrupt Controller (NVIC)

The Nested Vectored Interrupt Controller (NVIC) is an integral part of the Cortex-M0. The tight coupling to the CPU allows for low interrupt latency and efficient processing of late arriving interrupts.

7.5.1 Features

- Controls system exceptions and peripheral interrupts.

- Bidirectional data transfer between masters and slaves.
- Multi-master bus (no central master).
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus.
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus.
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer.
- The I^2C-bus can be used for test and diagnostic purposes.
- The I^2C-bus controller supports multiple address recognition and a bus monitor mode.

7.13 10-bit ADC

The LPC122x contains one ADC. It is a single 10-bit successive approximation ADC with eight channels.

7.13.1 Features

- 10-bit successive approximation ADC.
- Input multiplexing among 8 pins.
- Power-down mode.
- Measurement range 0 V to $V_{DD(3V3)}$.
- 10-bit conversion time of 257 kHz.
- Burst conversion mode for single or multiple inputs.
- Optional conversion on transition of input pin or counter/timer match signal.
- Individual result registers for each ADC channel to reduce interrupt overhead.

7.14 Comparator block

The comparator block consists of two analog comparators.

7.14.1 Features

- Up to six selectable external sources per comparator; fully configurable on either positive or negative comparator input channels.
- BOD 0.9 V internal reference voltage selectable on both comparators; configurable on either positive or negative comparator input channels.
- 32-stage voltage ladder internal reference voltage selectable on both comparators; configurable on either positive or negative comparator input channels.
- Voltage ladder source voltage is selectable from an external pin or an internal 3.3 V voltage rail if external power source is not available.
- Voltage ladder can be separately powered down for applications only requiring the comparator function.
- Relaxation oscillator circuitry output for a feedback 555-style timer application.
- Common interrupt connected to NVIC.
- Comparator outputs selectable as synchronous or asynchronous.

In Sleep mode, execution of instructions is suspended until either a reset or interrupt occurs. Peripheral functions continue operation during Sleep mode and may generate interrupts to cause the processor to resume execution. Sleep mode eliminates dynamic power used by the processor itself, memory systems and related controllers, and internal buses.

7.18.5.2 Deep-sleep mode

In Deep-sleep mode, the chip is in Sleep mode, and in addition all analog blocks are shut down. As an exception, the user has the option to keep the watchdog oscillator and the BOD circuit running for self-timed wake-up and BOD protection. Deep-sleep mode allows for additional power savings.

The GPIO pins PIO0_0 to PIO0_11 (up to 12 pins total) and the RTC match interrupt can serve as a wake-up input to the start logic to wake up the chip from Deep-sleep mode.

Unless the watchdog oscillator is selected to run in Deep-sleep mode, the clock source should be switched to IRC before entering Deep-sleep mode, because the IRC can be switched on and off glitch-free.

7.18.5.3 Deep power-down mode

In Deep power-down mode, power is shut off to the entire chip with the exception of the Real Time Clock, the four general-purpose registers, and the WAKEUP pin. The LPC122x can wake up from Deep power-down mode via the WAKEUP pin or the RTC match interrupt.

When entering Deep power-down mode, an external pull-up resistor is required on the WAKEUP pin to hold it HIGH. The $\overline{\text{RESET}}$ pin must also be held HIGH to prevent it from floating while in Deep power-down mode.

7.19 System control

7.19.1 Start logic

The start logic connects external pins to corresponding interrupts in the NVIC. Each pin shown in Table 3 as input to the start logic has an individual interrupt in the NVIC interrupt vector table. The start logic pins can serve as external interrupt pins when the chip is running. In addition, an input signal on the start logic pins can wake up the chip from Deep-sleep mode when all clocks are shut down.

The start logic must be configured in the system configuration block and in the NVIC before being used.

7.19.2 Reset

Reset has four sources on the LPC122x: the $\overline{\text{RESET}}$ pin, the Watchdog reset, power-on reset (POR), and the BrownOut Detection (BOD) circuit. The $\overline{\text{RESET}}$ pin is a Schmitt trigger input pin. Assertion of chip reset by any source, once the operating voltage attains a usable level, starts the IRC and initializes the flash controller.

When the internal Reset is removed, the processor begins executing at address 0, which is initially the Reset vector mapped from the boot block. At that point, all of the processor and peripheral registers have been initialized to predetermined values.

7.20 Emulation and debugging

Debug functions are integrated into the ARM Cortex-M0. Serial wire debug is supported.

7.21 Integer division routines

The LPC122x contain performance-optimized integer division routines with support for up to 32-bit width in the numerator and denominator. Routines for signed and unsigned division and division with remainder are available. The integer division routines are ROM-based to reduce code-size.

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).[1]

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DD(3V3)}$	supply voltage (3.3 V)			3.0	3.6	V
$V_{DD(IO)}$	input/output supply voltage			3.0	3.6	V
V_I	input voltage	on all digital pins	[2]	−0.5	+3.6	V
		on pins PIO0_10 and PIO0_11 (I^2C-bus pins)		0	5.5	V
I_{DD}	supply current	per supply pin	[3]	-	100	mA
I_{SS}	ground current	per ground pin	[3]	-	100	mA
I_{latch}	I/O latch-up current	$-(0.5V_{DD}) < V_I < (1.5V_{DD})$; $T_j < 125$ °C		-	100	mA
T_{stg}	storage temperature		[4]	−65	+150	°C
$P_{tot(pack)}$	total power dissipation (per package)	based on package heat transfer, not device power consumption		-	1.5	W
V_{ESD}	electrostatic discharge voltage	human body model; all pins	[5]	−8000	+8000	V

[1] The following applies to the limiting values:

a) This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maximum.

b) Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

[2] Including voltage on outputs in 3-state mode.

[3] The peak current is limited to 25 times the corresponding maximum current.

[4] Dependent on package type.

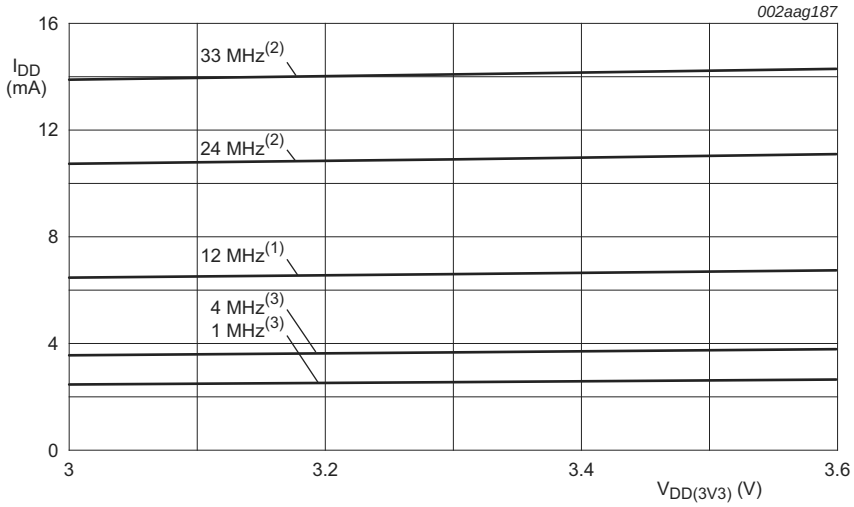
[5] Human body model: equivalent to discharging a 100 pF capacitor through a 1.5 kΩ series resistor.

10. Static characteristics

Table 7. Static characteristics

T_{amb} = −40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
$V_{DD(IO)}$	input/output supply voltage	on pin $V_{DD(IO)}$	3.0	3.3	3.6	V
$V_{DD(3V3)}$	supply voltage (3.3 V)		3.0	3.3	3.6	V
I_{DD}	supply current	Active mode; $V_{DD(3V3)}$ = 3.3 V; T_{amb} = 25 °C; code `while(1){}` executed from flash				
		all peripherals disabled:				
		CCLK = 12 MHz	-	4.6	-	mA
		CCLK = 24 MHz	-	9	-	mA
		CCLK = 33 MHz	-	12.2	-	mA
		all peripherals enabled:				
		CCLK = 12 MHz	-	6.6	-	mA
		CCLK = 24 MHz	-	10.9	-	mA
		CCLK = 33 MHz	-	14.1	-	mA
		Sleep mode; $V_{DD(3V3)}$ = 3.3 V; T_{amb} = 25 °C; all peripherals disabled				
		CCLK = 12 MHz	-	1.8	-	mA
		CCLK = 24 MHz	-	3.3	-	mA
		CCLK = 33 MHz	-	4.4	-	mA
		Deep-sleep mode; $V_{DD(3V3)}$ = 3.3 V; T_{amb} = 25 °C	-	30	-	μA
		Deep power-down mode; $V_{DD(3V3)}$ = 3.3 V; T_{amb} = 25 °C	-	720	-	nA
Normal-drive output pins (Standard port pins, RESET)						
I_{IL}	LOW-level input current	V_I = 0 V;	-	-	100	nA
I_{IH}	HIGH-level input current	$V_I = V_{DD(IO)}$;	-	-	100	nA
I_{OZ}	OFF-state output current	V_O = 0 V; $V_O = V_{DD(IO)}$;	-	-	100	nA
V_I	input voltage	pin configured to provide a digital function [2][3][4]	0	-	$V_{DD(IO)}$	V
V_O	output voltage	output active	0	-	$V_{DD(IO)}$	V
V_{IH}	HIGH-level input voltage		$0.7V_{DD(IO)}$	-	-	V



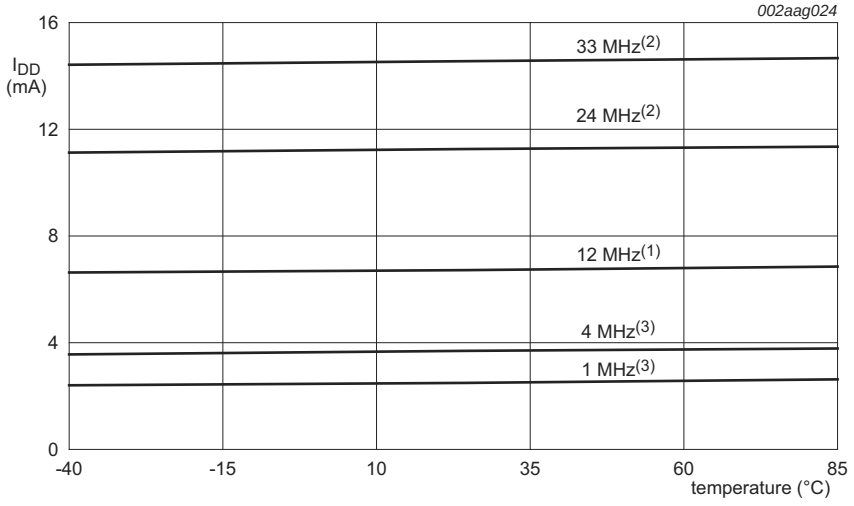
Conditions: T_{amb} = 25 °C; active mode entered executing code `while(1){}` from flash; all peripherals enabled in the SYSAHBCLKCTRL register.

(1) System oscillator and system PLL disabled; IRC enabled.

(2) System oscillator and system PLL enabled; IRC disabled.

(3) System oscillator enabled with external clock input; IRC and system PLL disabled.

Fig 8. Active mode: Typical supply current I_{DD} versus supply voltage $V_{DD(3V3)}$ for different system clock frequencies (all peripherals enabled)



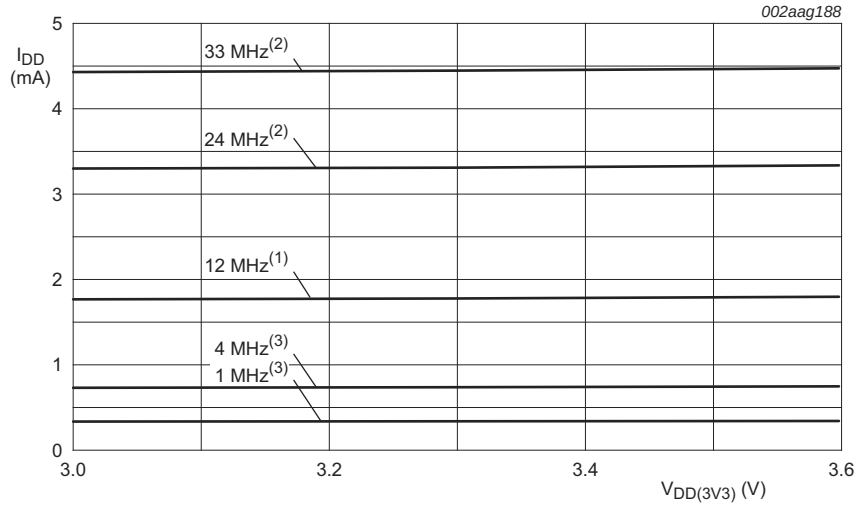
Conditions: $V_{DD(3V3)}$ = 3.3 V; active mode entered executing code `while(1){}` from flash; all peripherals enabled in the SYSAHBCLKCTRL register.

(1) System oscillator and system PLL disabled; IRC enabled.

(2) System oscillator and system PLL enabled; IRC disabled.

(3) System oscillator enabled with external clock input; IRC and system PLL disabled.

Fig 9. Active mode: Typical supply current I_{DD} versus temperature for different system clock frequencies (peripherals enabled)



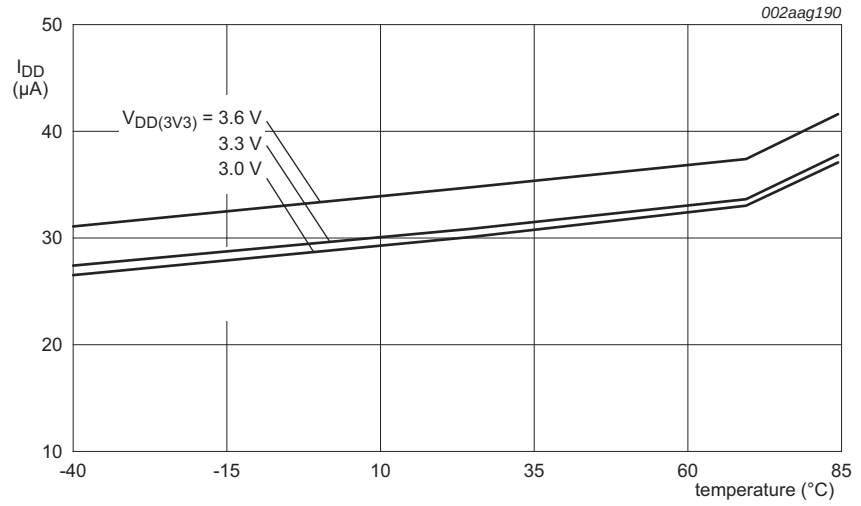
Conditions: $V_{DD(3V3)}$ = 3.3 V; sleep mode entered from flash; all peripherals disabled in the SYSAHBCLKCTRL register (SYSAHBCLKCTRL = 0x1F); all peripheral clocks disabled; internal pull-up resistors disabled; BOD disabled.

(1) System oscillator and system PLL disabled; IRC enabled.

(2) System oscillator and system PLL enabled; IRC disabled.

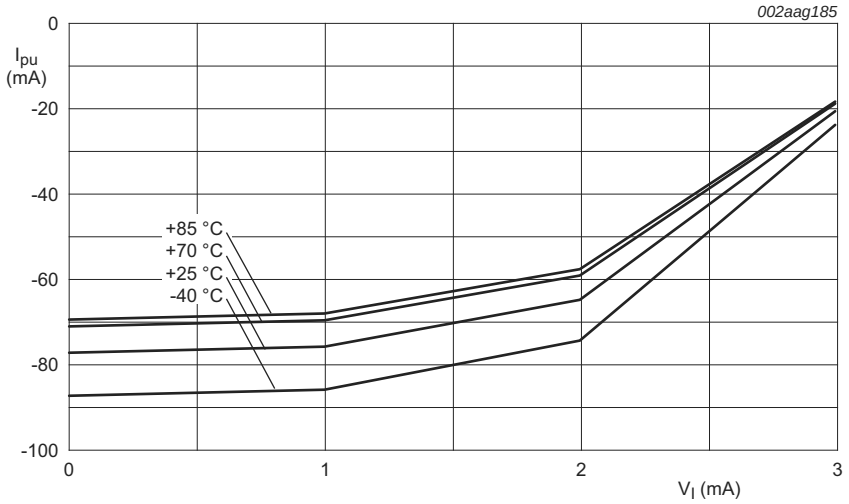
(3) System oscillator enabled with external clock input; IRC and system PLL disabled.

Fig 10. Sleep mode: Typical supply current I_{DD} versus supply voltage $V_{DD(3V3)}$ for different system clock frequencies



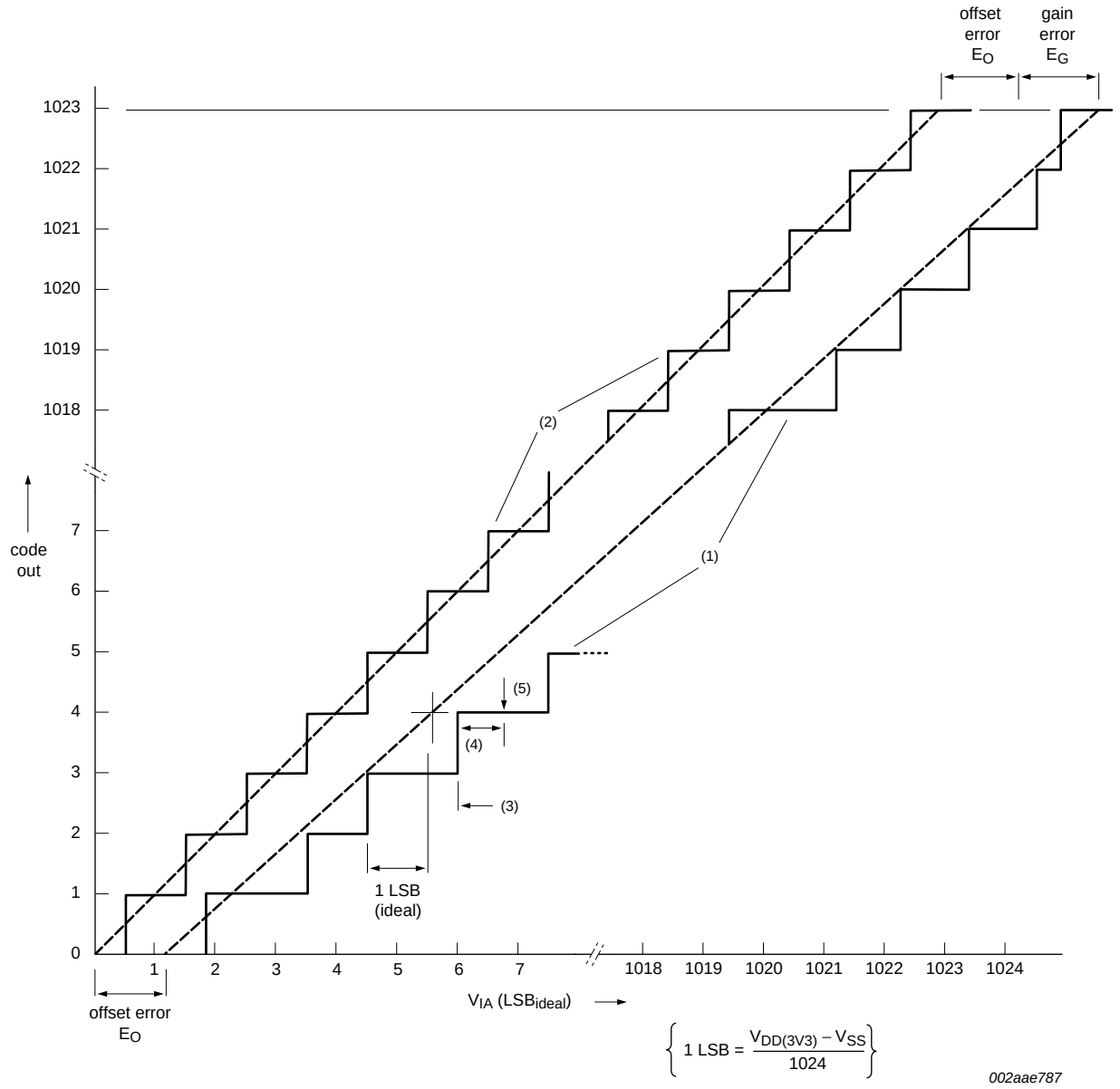
Conditions: BOD disabled; all oscillators and analog blocks disabled in the PDSLEEPCFG register

Fig 11. Deep-sleep mode: Typical supply current I_{DD} versus temperature for different supply voltages $V_{DD(3V3)}$



Conditions: $V_{DD(IO)}$ = 3.3 V.

Fig 18. Typical pull-up current I_{pu} versus input voltage V_I



(1) Example of an actual transfer curve.

(2) The ideal transfer curve.

(3) Differential linearity error (E_D).

(4) Integral non-linearity ($E_{L(adj)}$).

(5) Center of a step of the actual transfer curve.

Fig 19. ADC characteristics

10.5 BOD static characteristics

Table 10. BOD static characteristics[1]
T_{amb} = 25 °C.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{th}	threshold voltage	interrupt level 1				
		assertion	-	2.25	-	V
		de-assertion	-	2.39	-	V
		interrupt level 2				
		assertion	-	2.54	-	V
		de-assertion	-	2.67	-	V
		interrupt level 3				
		assertion	-	2.83	-	V
		de-assertion	-	2.93	-	V
		reset level 1				
		assertion	-	2.04	-	V
		de-assertion	-	2.18	-	V
		reset level 2				
		assertion	-	2.34	-	V
		de-assertion	-	2.47	-	V
		reset level 3				
		assertion	-	2.62	-	V
		de-assertion	-	2.76	-	V

[1] Interrupt levels are selected by writing the level value to the BOD control register BODCTRL, see *LPC122x user manual*.

12.3 ElectroMagnetic Compatibility (EMC)

Radiated emission measurements according to the IEC61967-2 standard using the TEM-cell method are shown for the LPC1227FBD64/301 in Table 17.

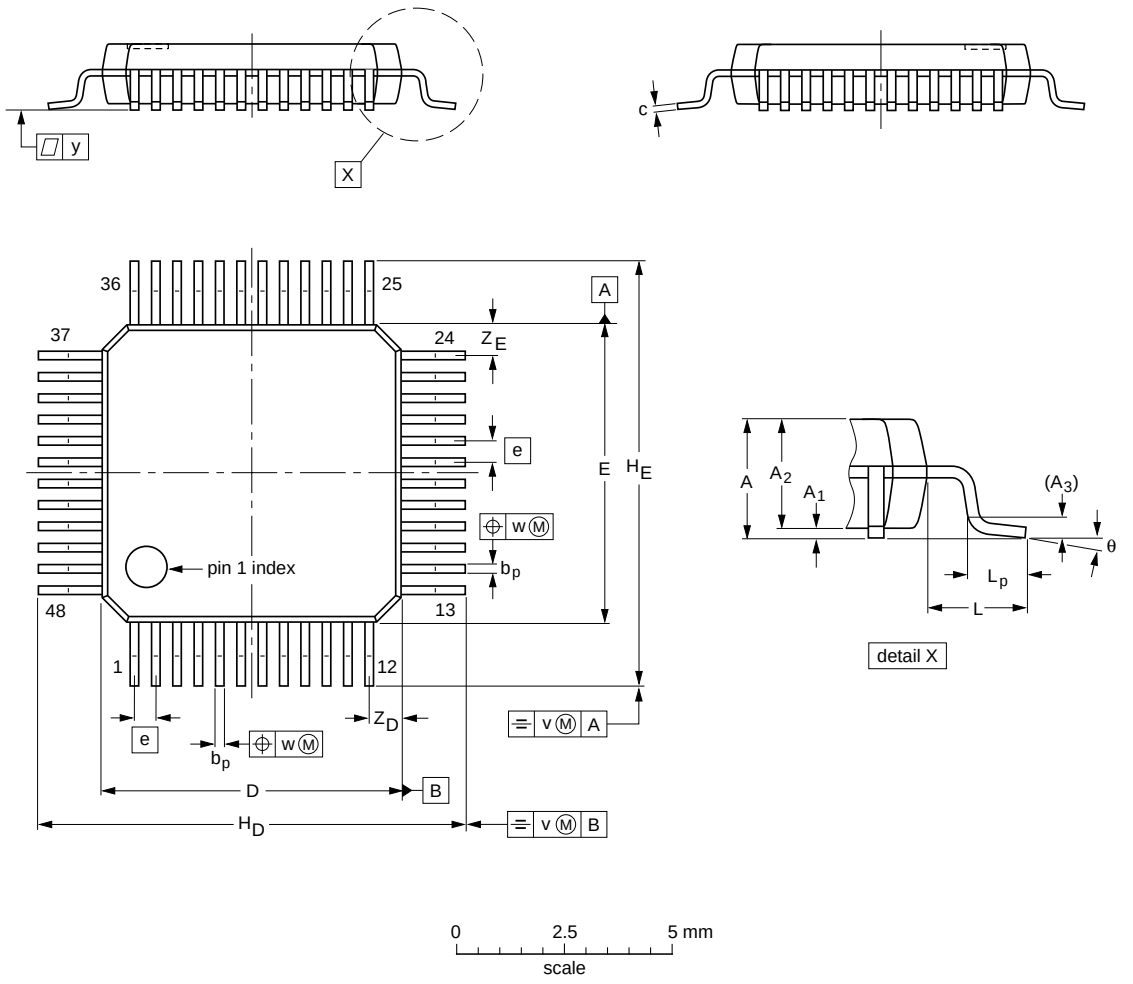
Table 17. ElectroMagnetic Compatibility (EMC) for part LPC1227FBD64/301 (TEM-cell method)

V_{DD} = 3.3 V; T_{amb} = 25 °C.

Parameter	Frequency band	System clock =			Unit
		12 MHz	24 MHz	33 MHz	
Input clock: IRC (12 MHz)					
maximum peak level	150 kHz - 30 MHz	−4.2	−3.8	−6.4	dBμV
	30 MHz - 150 MHz	7.3	5.4	9	dBμV
	150 MHz - 1 GHz	16.4	20.1	23.4	dBμV
IEC level[1]	-	M	L	L	-
Input clock: crystal oscillator (12 MHz)					
maximum peak level	150 kHz - 30 MHz	−4.8	−4	−6.6	dBμV
	30 MHz - 150 MHz	6.9	5.6	10	dBμV
	150 MHz - 1 GHz	16.3	20.3	22.3	dBμV
IEC level[1]	-	M	L	L	-

[1] IEC levels refer to *Appendix D in the IEC61967-2 Specification*.

LQFP48: plastic low profile quad flat package; 48 leads; body 7 x 7 x 1.4 mm **SOT313-2**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_D	H_E	L	L_p	v	w	y	$Z_D^{(1)}$	$Z_E^{(1)}$	θ
mm	1.6	0.20 0.05	1.45 1.35	0.25	0.27 0.17	0.18 0.12	7.1 6.9	7.1 6.9	0.5	9.15 8.85	9.15 8.85	1	0.75 0.45	0.2	0.12	0.1	0.95 0.55	0.95 0.55	7^o 0^o

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT313-2	136E05	MS-026				~~00-01-19~~ 03-02-25

Fig 26. Package outline SOT313-2 (LQFP48)

17. Legal information

17.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

17.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

Product specification — The information and data provided in a Product data sheet shall define the specification of the product as agreed between NXP Semiconductors and its customer, unless NXP Semiconductors and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the NXP Semiconductors product is deemed to offer functions and qualities beyond those described in the Product data sheet.

17.3 Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

NXP Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

Terms and conditions of commercial sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at http://www.nxp.com/profile/terms, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NXP Semiconductors hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of NXP Semiconductors products by customer.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from national authorities.

19. Contents

continued >>